



FF1738 - Pb/Sn SOLDER BALLS
FFG1738 - Sn/Ag/Cu SOLDER BALLS

SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	2.85	\approx	3.25	2
A ₁	0.40	0.50	0.60	
A ₂	1.00	\approx	1.40	
D/E	42.50 BASIC			
D ₁ /E ₁	41.00 REF			
e	1.00 BASIC			
phi b	0.50	0.60	0.70	
aaa	\approx	\approx	0.20	
bbb	\approx	\approx	0.25	
ddd	\approx	\approx	0.25	
eee	\approx	\approx	0.10	
M	42			

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994
2. SYMBOL "M" IS THE PIN MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAV-1 (DEPOPULATED)

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
07/13/07	1.0	Initial Xilinx release.
10/11/10	1.1	Changed the overall package thickness (symbol A) from 2.70 min – 3.50 max to 2.85 min – 3.25 max.
03/12/12	1.2	Added FFG1738 packaging information (solder ball composition). Updated copyright and trademark notice and Notice of Disclaimer .

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